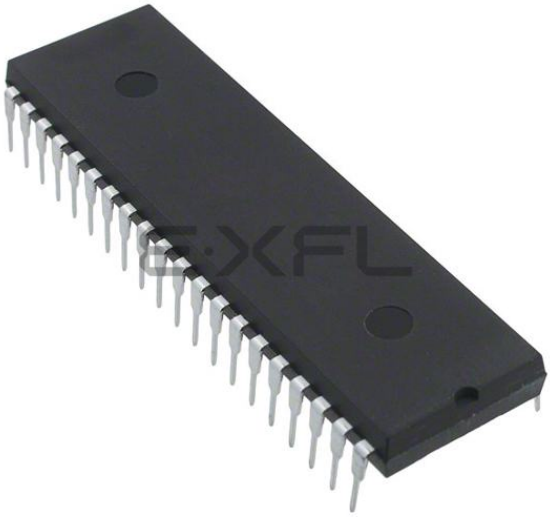

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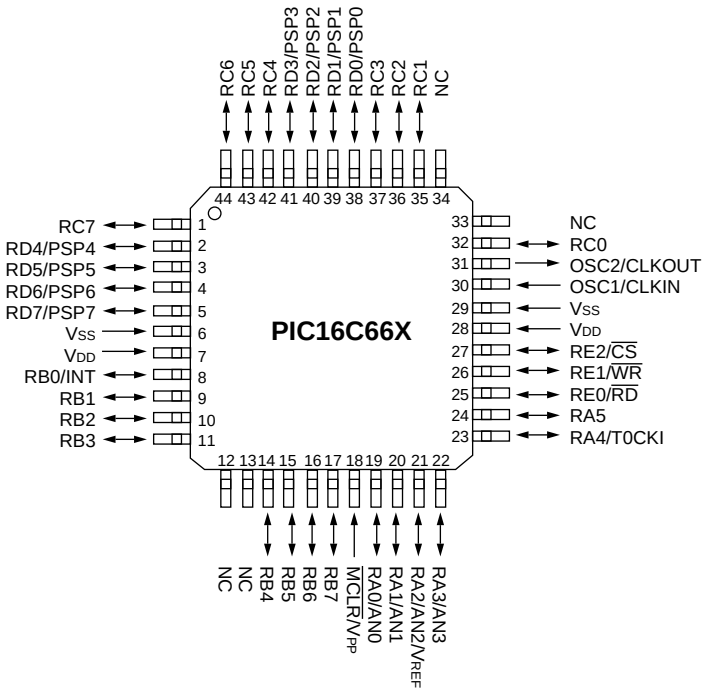
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

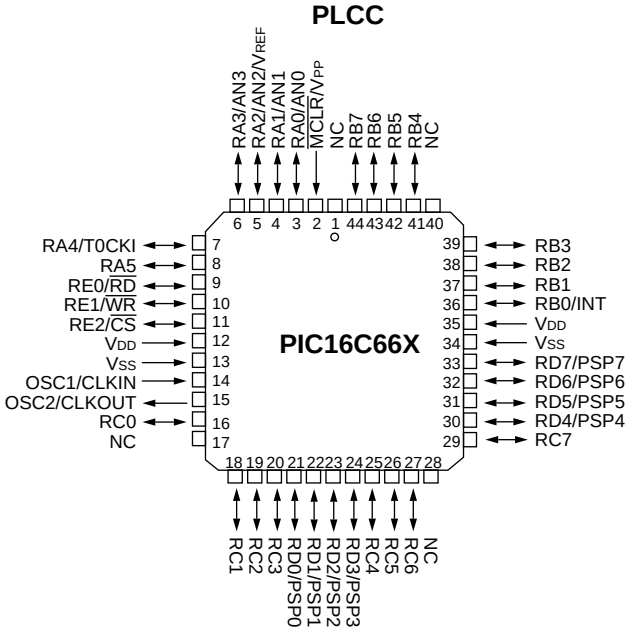
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, LED, POR, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	176 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c662-04i-p

Pin Diagrams (Cont.'d)

TQFP



PLCC



1.0 GENERAL DESCRIPTION

PIC16C64X & PIC16C66X devices are 28-pin and 40-pin EPROM-based members of the versatile PIC16CXXX family of low-cost, high-performance, CMOS, fully-static, 8-bit microcontrollers.

All PIC16/17 microcontrollers employ an advanced RISC architecture. The PIC16CXXX family has enhanced core features, eight-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 14-bit wide instruction word with the separate 8-bit wide data. The two-stage instruction pipeline allows all instructions to execute in a single-cycle, except for program branches (which require two cycles). A total of 35 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance.

PIC16CXXX microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in its class.

The PIC16C641 has 128 bytes of RAM and the PIC16C642 has 176 bytes of RAM. Both devices have 22 I/O pins, and an 8-bit timer/counter with an 8-bit programmable prescaler. In addition, they have two analog comparators with a programmable on-chip voltage reference module. Program Memory has internal parity error detection circuitry with a Parity Error Reset. The comparator module is ideally suited for applications requiring a low-cost analog interface (e.g., battery chargers, threshold detectors, white goods controllers, etc.).

The PIC16C661 has 128 bytes of RAM and the PIC16C662 has 176 bytes of RAM. Both devices have 33 I/O pins, and an 8-bit timer/counter with an 8-bit programmable prescaler. They also have an 8-bit Parallel Slave Port. In addition, the devices have two analog comparators with a programmable on-chip voltage reference module. Program Memory has internal parity error detection circuitry with a Parity Error Reset. The comparator module is ideally suited for applications requiring a low-cost analog interface (e.g., battery chargers, threshold detectors, white goods controllers, etc.).

PIC16CXXX devices have special features to reduce external components, thus reducing cost, enhancing system reliability and reducing power consumption. There are four oscillator options, of which the single pin RC oscillator provides a low-cost solution, the LP oscillator minimizes power consumption, XT is a standard crystal, and the HS is for High Speed crystals. The SLEEP (power-down) mode offers power saving. The user can wake-up the chip from SLEEP through several external and internal interrupts and resets.

A highly reliable Watchdog Timer (WDT) with its own on-chip RC oscillator provides protection against software lock-up.

A UV-erasable CERDIP-packaged version is ideal for code development while the cost-effective One-Time Programmable (OTP) version is suitable for production in any volume.

The PIC16CXXX series fit perfectly in applications ranging from battery chargers to low-power remote sensors. The EPROM technology makes customization of application programs (detection levels, pulse generation, timers, etc.) extremely fast and convenient. The small footprint packages make this microcontroller series perfect for all applications with space limitations. Low-cost, low-power, high-performance, ease of use, and I/O flexibility make the PIC16C64X & PIC16C66X very versatile.

1.1 Family and Upward Compatibility

Those users familiar with the PIC16C5X family of microcontrollers will realize that this is an enhanced version of the PIC16C5X architecture. Please refer to Appendix A for a detailed list of enhancements. Code written for PIC16C5X can be easily ported to the PIC16C64X & PIC16C66X (Appendix B).

1.2 Development Support

PIC16C64X & PIC16C66X devices are supported by the complete line of Microchip Development tools, including:

- MPLAB Integrated Development Environment including MPLAB-Simulator.
- MPASM Universal Assembler and MPLAB-C Universal C compiler.
- PRO MATE II and PICSTART Plus device programmers.
- PICMASTER In-circuit Emulator System
- *fuzzy*TECH-MP Fuzzy Logic Development Tools
- DriveWay Visual Programming Tool

Please refer to Section 11.0 for more details about these and other Microchip development tools.

6.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control, i.e., it can be changed “on the fly” during program execution.

Note:	To avoid an unintended device RESET, the following instruction sequence (shown in Example 6-1) must be executed when changing the prescaler assignment from Timer0 to the WDT. This precaution must be followed even if the WDT is disabled.

EXAMPLE 6-1: CHANGING PRESCALER (TIMER0→WDT)

```
BCF     STATUS, RP0  ;Bank 0
CLRF    TMR0         ;Clear TMR0 & Prescaler
BSF     STATUS, RP0  ;Bank 1
CLRWDT               ;Clears WDT
MOVLW   b'xxxx1xxx'  ;Select new prescale
MOVWF   OPTION_REG   ;value & WDT
BCF     STATUS, RP0  ;Bank 0
```

To change prescaler from the WDT to the Timer0 module, use the sequence shown in Example 6-2.

EXAMPLE 6-2: CHANGING PRESCALER (WDT→TIMER0)

```
CLRWDT               ;Clear WDT and
                     ;prescaler
BSF     STATUS, RP0  ;Bank 1
MOVLW   b'xxxx0xxx'  ;Select TMR0, new
                     ;prescale value and
MOVWF   OPTION_REG   ;clock source
BCF     STATUS, RP0  ;Bank 0
```

TABLE 6-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
01h	TMR0	Timer0 module’s register								xxxx xxxx	uuuu uuuu
0Bh/8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
81h	OPTION	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	--11 1111	--11 1111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by Timer0.

7.6 Comparator Interrupts

The comparator interrupt flag is set whenever there is a change in the output value of either comparator. User software will need to maintain information about the status of the output bits, as read from CMCON<7:6>, to determine the actual change that has occurred. The CMIF bit (PIR1<6>), is the comparator interrupt flag and must be cleared in user software.

To enable the Comparator interrupt the following bits must be set:

- CMIE (PIE1<6>)
- PEIE (INTCON<6>)
- GIE (INTCON<7>)

The user, in the interrupt service routine, can clear the interrupt in the following manner:

a) Any read or write of CMCON. This will end the mismatch condition.

b) Clear flag bit CMIF.

A mismatch condition will continue to set flag bit CMIF. Reading CMCON will end the mismatch condition, and allow flag bit CMIF to be cleared.

7.7 Comparator Operation During SLEEP

When a comparator is active and the device is placed in SLEEP mode, the comparator remains active and the interrupt is functional if enabled. This interrupt will wake up the device from SLEEP mode when enabled. While the comparator is powered up, higher sleep currents than shown in the power-down current specification will occur. Each comparator that is operational will consume additional current as shown in the comparator specifications. To minimize power consumption while in SLEEP mode, turn off the comparators, CM2:CM0 = 111, before entering sleep. If the device wakes up from sleep, the contents of the CMCON register are not affected.

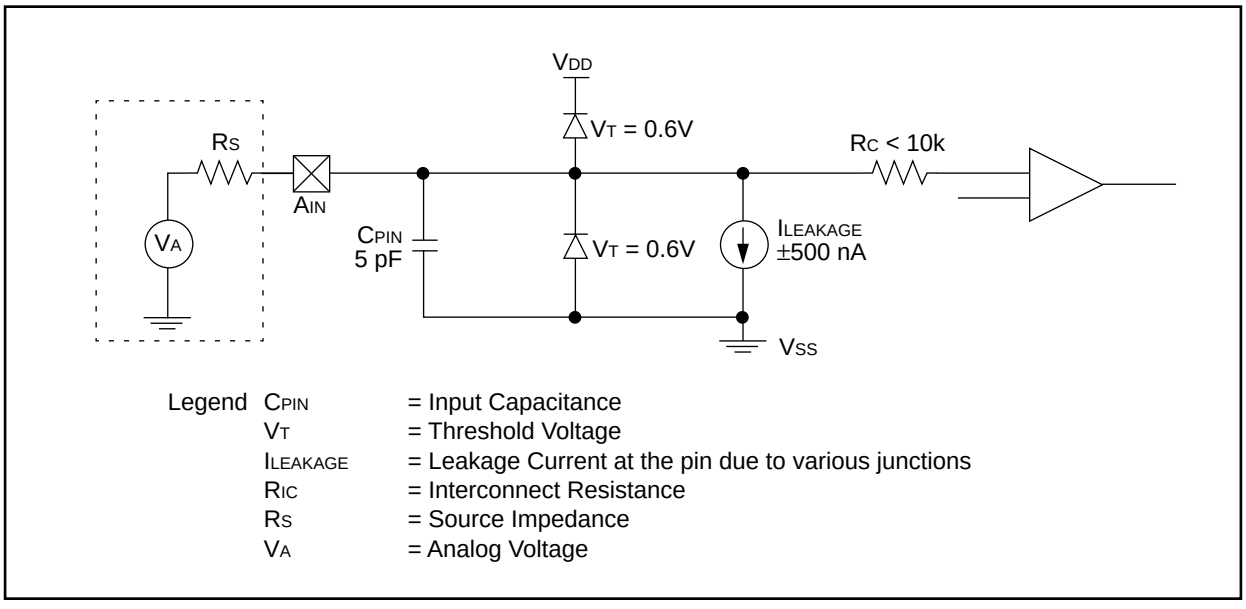
7.8 Effects of a RESET

A device reset forces the CMCON register to its reset state. This forces the comparator module to be in the comparator reset mode, CM2:CM0 = 000. This ensures that all potential inputs are analog inputs. Device current is minimized when analog inputs are present at reset time. The comparators will be powered down during the reset interval.

7.9 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 7-5. Since the analog pins are connected to a digital output, they have reverse biased diodes to V_{DD} and V_{SS}. The analog input therefore, must be between V_{SS} and V_{DD}. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur. A maximum source impedance of 10 kΩ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 7-5: ANALOG INPUT MODEL



9.1 Configuration Bits

The configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space. In fact, it belongs to the special test/configuration memory space (2000h–3FFFh), which can be accessed only during programming.

FIGURE 9-1: CONFIGURATION WORD

CP1	CP0	CP1	CP0	CP1	CP0	MPEEN	BODEN	CP1	CP0	$\overline{\text{PWRTE}}$	WDTE	FOSC1	FOSC0
bit13													bit0

CONFIG REGISTER: Address 2007h

bit 13-8 5-4: **CP1:CP0:** Code protection bits(2)
- 11 = Code protection off
- 10 = Upper half of program memory code protected
- 01 = Upper 3/4th of program memory code protected
- 00 = All memory is code protected

bit 7: **MPEEN**: Memory Parity Error Enable
- 1 = Memory Parity Checking is enabled
- 0 = Memory Parity Checking is disabled

bit 6: **BODEN**: Brown-out Reset Enable bit (1)
- 1 = BOR enabled
- 0 = BOR disabled

bit 3: **$\overline{\text{PWRTE}}$**: Power-up Timer Enable bit (1)
- 1 = PWRT disabled
- 0 = PWRT enabled

bit 2: **WDTE**: Watchdog Timer Enable bit
- 1 = WDT enabled
- 0 = WDT disabled

bit 1-0: **FOSC1:FOSC0**: Oscillator Selection bits
- 11 = RC oscillator
- 10 = HS oscillator
- 01 = XT oscillator
- 00 = LP oscillator

Note 1: Enabling Brown-out Reset automatically enables the Power-up Timer (PWRT) regardless of the value of bit $\overline{\text{PWRTE}}$. Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled.

2: All of the CP1:CP0 pairs have to be given the same value to enable the code protection scheme listed.

9.2 Oscillator Configurations

9.2.1 OSCILLATOR TYPES

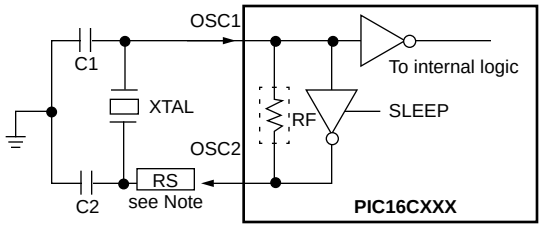
The PIC16CXXX can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

9.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT, LP or HS modes a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation (Figure 9-2). The PIC16CXXX oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1 pin (Figure 9-3).

FIGURE 9-2: CRYSTAL OPERATION (OR CERAMIC RESONATOR) (HS, XT OR LP OSC CONFIGURATION)



See Table 9-1 or Table 9-2 for recommended values of C1 and C2.

Note: A series resistor may be required for AT strip cut crystals.

FIGURE 9-3: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

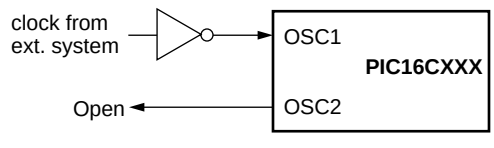


TABLE 9-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS (PRELIMINARY)

Ranges tested:		
Mode	**Freq**	**OSC1**
XT	455 kHz 2.0 MHz 4.0 MHz	22 - 100 pF 15 - 68 pF 15 - 68 pF
HS	8.0 MHz 16.0 MHz	10 - 68 pF 10 - 22 pF

Note: Recommended values of C1 and C2 are identical to the ranges tested table.
Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

Resonators used:		
455 kHz	Panasonic EFO-A455K04B	±0.3%
2.0 MHz	Murata Erie CSA2.00MG	±0.5%
4.0 MHz	Murata Erie CSA4.00MG	±0.5%
8.0 MHz	Murata Erie CSA8.00MT	±0.5%
16.0 MHz	Murata Erie CSA16.00MX	±0.5%

All resonators used did not have built-in capacitors.

TABLE 9-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR (PRELIMINARY)

Mode	Freq	OSC1	OSC2
LP	32 kHz 200 kHz	68 - 100 pF 15 - 30 pF	68 - 100 pF 15 - 30 pF
XT	100 kHz 2 MHz 4 MHz	68 - 150 pF 15 - 30 pF 15 - 30 pF	150 - 200 pF 15 - 30 pF 15 - 30 pF
HS	8 MHz 10 MHz 20 MHz	15 - 30 pF 15 - 30 pF 15 - 30 pF	15 - 30 pF 15 - 30 pF 15 - 30 pF

Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

Crystals used:		
32.768 kHz	Epson C-001R32.768K-A	± 20 PPM
100 kHz	Epson C-2 100.00 KC-P	± 20 PPM
200 kHz	STD XTL 200.000 kHz	± 20 PPM
2.0 MHz	ECS ECS-20-S-2	± 50 PPM
4.0 MHz	ECS ECS-40-S-4	± 50 PPM
10.0 MHz	ECS ECS-100-S-4	± 50 PPM
20.0 MHz	ECS ECS-200-S-4	± 50 PPM

9.4.5 PARITY ERROR RESET (PER)

PIC16C64X & PIC16C66X devices have on-chip parity bits that can be used to verify the contents of program memory. Parity bits may be useful in applications in order to increase overall reliability of a system.

There are two parity bits for each word of Program Memory. The parity bits are computed on alternating bits of the program word. One computation is performed using even parity, the other using odd parity. As a program executes, the parity is verified. The even parity bit is XOR'd with the even bits in the program memory word. The odd parity bit is negated and XOR'd with the odd bits in the program memory word. When an error is detected, a reset is generated and the $\overline{PER}$ flag bit in the PCON register is set. This indication can allow software to act on a failure. However, there is no indication of the program memory location of the failure of the Program Memory. This flag can only be cleared in software or by a POR.

The parity array is user selectable during programming. Bit7 of the configuration word located at address 2007h can be programmed (read as '0') to disable parity checking. If left unprogrammed (read as '1'), parity checking is enabled.

9.4.6 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows: First PWRT time-out is invoked after POR has expired. Then the OST is activated. The total time-out will vary based on oscillator configuration and $\overline{PWRTE}$ bit status. For example, in RC mode with the $\overline{PWRTE}$ bit set (PWRT disabled), there will be no time-out at all. Figure 9-9, Figure 9-10 and Figure 9-11 depict time-out sequences.

Since the time-outs occur from the POR pulse, if $\overline{MCLR}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{MCLR}$ high will begin execution immediately (Figure 9-10). This is useful for testing purposes or to synchronize more than one device operating in parallel.

Table 9-5 shows the reset conditions for some special registers, while Table 9-6 shows the reset conditions for all the registers.

9.4.7 POWER CONTROL/STATUS REGISTER (PCON)

The power control/status register, PCON (address 8Eh) has four bits. See Figure 4-10 for register.

Bit0 is $\overline{BOR}$ (Brown-out Reset). $\overline{BOR}$ is unknown on a Power-on-reset. It must initially be set by the user and checked on subsequent resets to see if $\overline{BOR}$ = '0' indicating that a Brown-out Reset has occurred. The $\overline{BOR}$ status bit is a "don't care" bit and is not necessarily predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the Configuration word).

Bit1 is $\overline{POR}$ (Power-on Reset). It is cleared on a Power-on Reset and is unaffected otherwise. The user set this bit following a Power-on Reset. On subsequent resets if $\overline{POR}$ is '0', it will indicate that a Power-on Reset must have occurred.

Bit2 is $\overline{PER}$ (Parity Error Reset). It is cleared on a Parity Error Reset and must be set by user software. It will also be set on a Power-on Reset.

Bit7 is MPEEN (Memory Parity Error Enable). This bit reflects the status of the MPEEN bit in configuration word. It is unaffected by any reset or interrupt.

TABLE 9-3: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out Reset	Wake-up from SLEEP
	$\overline{PWRTE}$ = 0	$\overline{PWRTE}$ = 1		
XT, HS, LP	72 ms + 1024 TOSC	1024 TOSC	72 ms + 1024 TOSC	1024 TOSC
RC	72 ms	—	72 ms	—

SUBLW **Subtract W from Literal**

Syntax: [*label*] SUBLW k

Operands: $0 \le k \le 255$

Operation: k - (W) → (W)

Status Affected: C, DC, Z

Encoding:

11	110x	kkkk	kkkk

Description: The W register is subtracted (2's complement method) from the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example 1:
```
SUBLW   0x02
```
Before Instruction
```
W = 1
C = ?
```
After Instruction
```
W = 1
C = 1; result is positive
```

Example 2: Before Instruction
```
W = 2
C = ?
```
After Instruction
```
W = 0
C = 1;  result is zero
```

Example 3: Before Instruction
```
W = 3
C = ?
```
After Instruction
```
W = 0xFF
C = 0; result is negative
```

SUBWF **Subtract W from f**

Syntax: [*label*] SUBWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - (W) → (dest)

Status Affected: C, DC, Z

Encoding:

00	0010	dfff	ffff

Description: Subtract (2's complement method) W register from register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example 1:
```
SUBWF   REG1,1
```
Before Instruction
```
REG1 = 3
W    = 2
C    = ?
```
After Instruction
```
REG1 = 1
W    = 2
C    = 1; result is positive
```

Example 2: Before Instruction
```
REG1 = 2
W    = 2
C    = ?
```
After Instruction
```
REG1 = 0
W    = 2
C    = 1; result is zero
```

Example 3: Before Instruction
```
REG1 = 1
W    = 2
C    = ?
```
After Instruction
```
REG1 = 0xFF
W    = 2
C    = 0; result is negative
```

NOTES:

12.2 DC Characteristics: PIC16LC641/642/661/662-04 (Commercial, Industrial)

Standard Operating Conditions (unless otherwise stated) Operating temperature –40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C commercial							
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	–	6.0	V	XT, RC, and LP osc configuration
D002*	VDR	RAM Data Retention Voltage (1)	1.5	–	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure internal Power-on Reset signal	–	VSS	–	V	See section on Power-on Reset for details
D004*	SVDD	VDD rise rate to ensure internal Power-on Reset signal	0.05	–	–	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Reset Voltage	3.7	4.0	4.3	V	BODEN configuration bit is clear
D010	IDD	Supply Current (2)	–	2.0	3.8	mA	XT and RC osc configuration FOSC = 4.0 MHz, VDD = 3.0V, WDT disabled (4)
D010A			–	22.5	48	µA	LP osc configuration FOSC = 32 kHz, VDD = 3.0V, WDT disabled
		Module Differential Current (5)					
D015	ΔIBOR	Brown-out Reset Current	–	350	425	µA	BODEN bit is clear, VDD = 5.0V
D016	ΔICOMP	Comparator Current for each Comparator	–	–	100	µA	VDD = 3.0V
D017	ΔIVREF	VREF Current	–	–	300	µA	VDD = 3.0V
D021	ΔIWDT	WDT Current	–	6.0	20	µA	VDD = 3.0V
D021	IPD	Power-down Current (3)	–	0.9	5	µA	VDD = 3.0V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1=external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,
MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

Standard Operating Conditions (unless otherwise stated)
Operating temperature –40°C ≤ TA ≤ +85°C for industrial,
0°C ≤ TA ≤ +70°C commercial, and
–40°C ≤ TA ≤ +125°C automotive
Operating voltage VDD range as described in DC spec Section 12.1 and 12.2

Param No.	Sym	Characteristic	Min	Typ †	Max	Unit	Conditions
	VOH	Output High Voltage (3)					
D090		I/O ports (Except RA4)	VDD-0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40° to +85°C
			VDD-0.7	-	-	V	IOH = -2.5 mA, VDD = 4.5V, +125°C
D092		OSC2/CLKOUT	VDD-0.7	-	-	V	IOH = -1.3 mA, VDD=4.5V, -40° to +85°C
		(RC only)	VDD-0.7	-	-	V	IOH = -1.0 mA, VDD = 4.5V, +125°C
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin	-	-	15	pF	In XT, HS and LP modes when external clock used to drive OSC1.
D101	CIO	All I/O pins/OSC2 (in RC mode)	-	-	50	pF	

* These parameters are characterized but not tested.

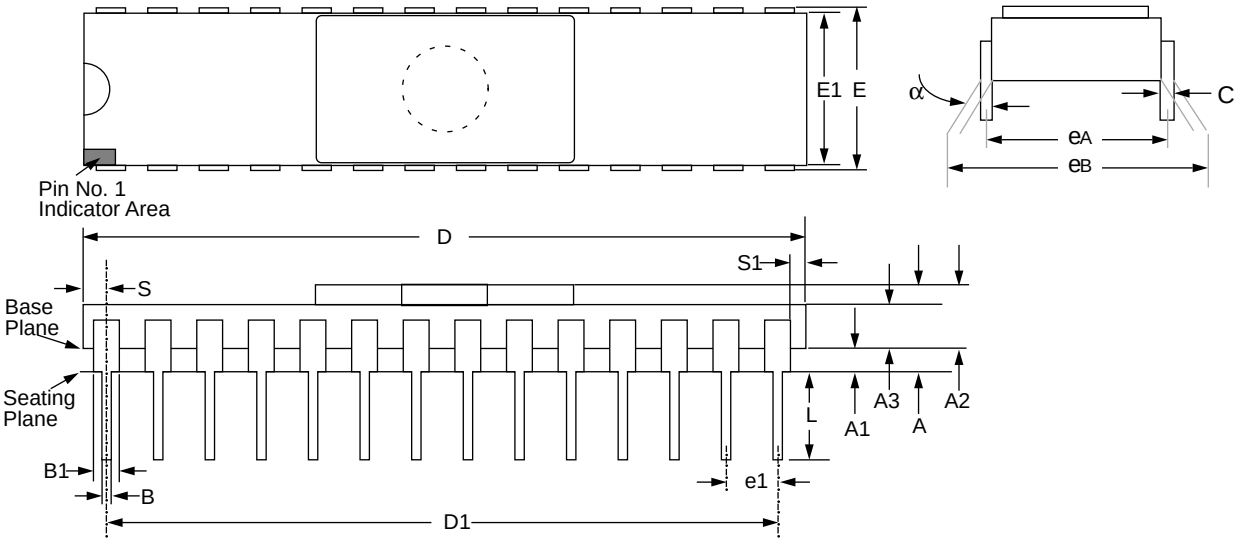
† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C64X & PIC16C66X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

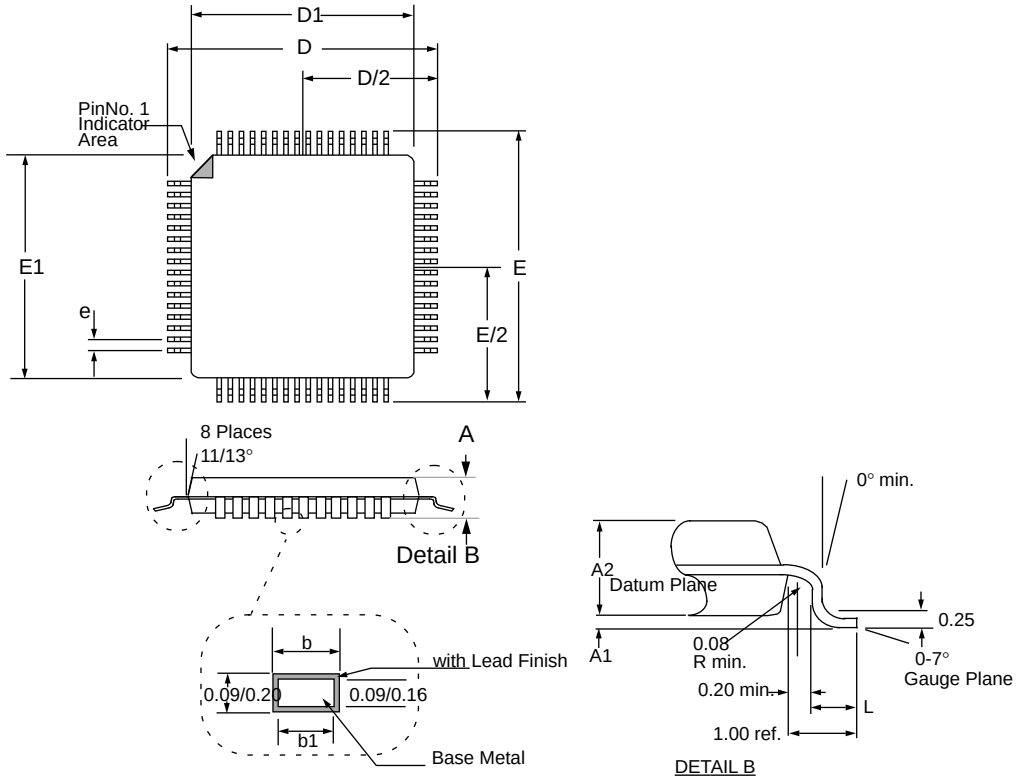
3: Negative current is defined as coming out of the pin.

Package Type: 28-Lead Ceramic Side Brazed Dual In-Line with Window (JW) (300 mil)



Package Group: Ceramic Side Brazed Dual In-Line (CER)						
Symbol	Millimeters			Inches		
	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	3.937	5.030		0.155	0.198	
A1	1.016	1.524		0.040	0.060	
A2	2.921	3.506		0.115	0.138	
A3	1.930	2.388		0.076	0.094	
B	0.406	0.508		0.016	0.020	
B1	1.219	1.321	**Typical**	0.048	0.052	
C	0.228	0.305	**Typical**	0.009	0.012	
D	35.204	35.916		1.386	1.414	
D1	32.893	33.147	**BSC**	1.295	1.305	
E	7.620	8.128		0.300	0.320	
E1	7.366	7.620		0.290	0.300	
e1	2.413	2.667	**Typical**	0.095	0.105	
eA	7.366	7.874	**BSC**	0.290	0.310	
eB	7.594	8.179		0.299	0.322	
L	3.302	4.064		0.130	0.160	
S	1.143	1.397		0.045	0.055	
S1	0.533	0.737		0.021	0.029	

Package Type: 44-Lead Thin Plastic Quad Flatpack (PT/TQ) - 10x10x1 mm Body 1.0/0.10 mm Lead Form

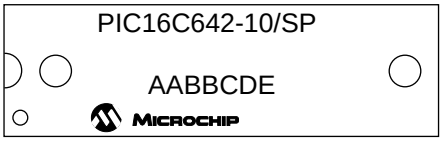


Package Group: Plastic TQFP						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	7°		0°	7°	
A	—	1.200		—	0.047	
A1	0.050	0.150		0.002	0.006	
A2	0.950	1.050		0.037	0.041	
b	0.300	0.450		0.012	0.018	
b1	0.300	0.400		0.012	0.016	
D	12.0	12.0	**BSC**	0.472	0.0472	**BSC**
D1	10.0	10.0	**BSC**	0.394	0.394	**BSC**
E	12.0	12.0	**BSC**	0.472	0.472	**BSC**
E1	10.0	10.0	**BSC**	0.394	0.394	**BSC**
e	0.8	0.8	**BSC**	0.031	0.031	**BSC**
L	0.450	0.750		0.018	0.030	

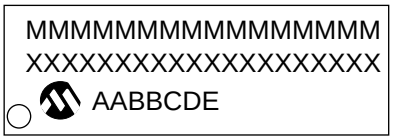
14.1 Package Marking Information

28-Lead PDIP (Skinny DIP)

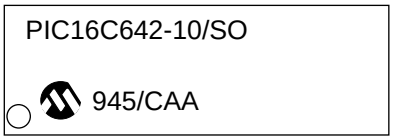
Example



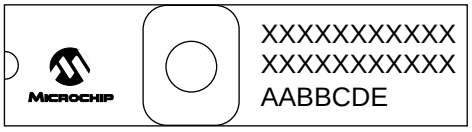
28-Lead SOIC



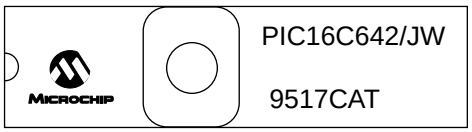
Example



28-Lead Side Brazed Skinny Windowed



Example



Legend:	MM...MMicrochip part number information
XX...X	Customer specific information*
AA	Year code (last 2 digits of calendar year)
BB	Week code (week of January 1 is week ‘01’)
C	Facility code of the plant at which wafer is manufactured C = Chandler, Arizona, U.S.A.
D	Mask revision number
E	Assembly code of the plant or country of origin in which part was assembled

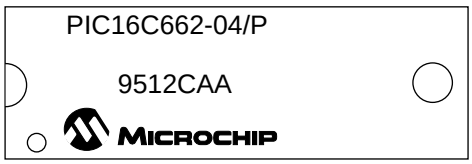
Note:In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

*****Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask rev#, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

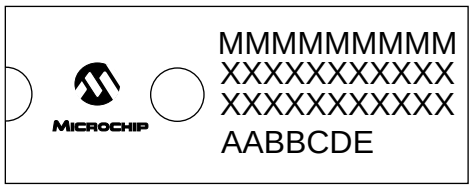
14.2 Package Marking Information

40-Lead PDIP

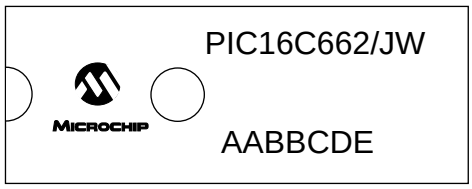
Example



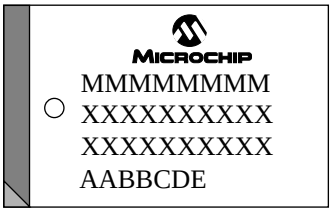
40-Lead CERDIP Windowed



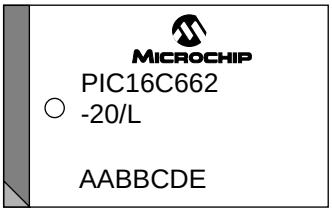
Example



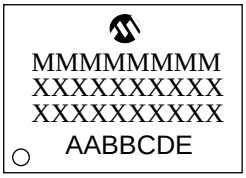
44-Lead PLCC



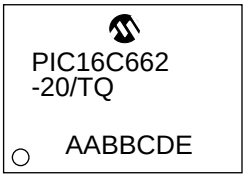
Example



44-Lead TQFP



Example



Legend:	MM...MMicrochip part number information
XX...X	Customer specific information*
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BB	Week code (week of January 1 is week ‘01’)
C	Facility code of the plant at which wafer is manufactured C = Chandler, Arizona, U.S.A.
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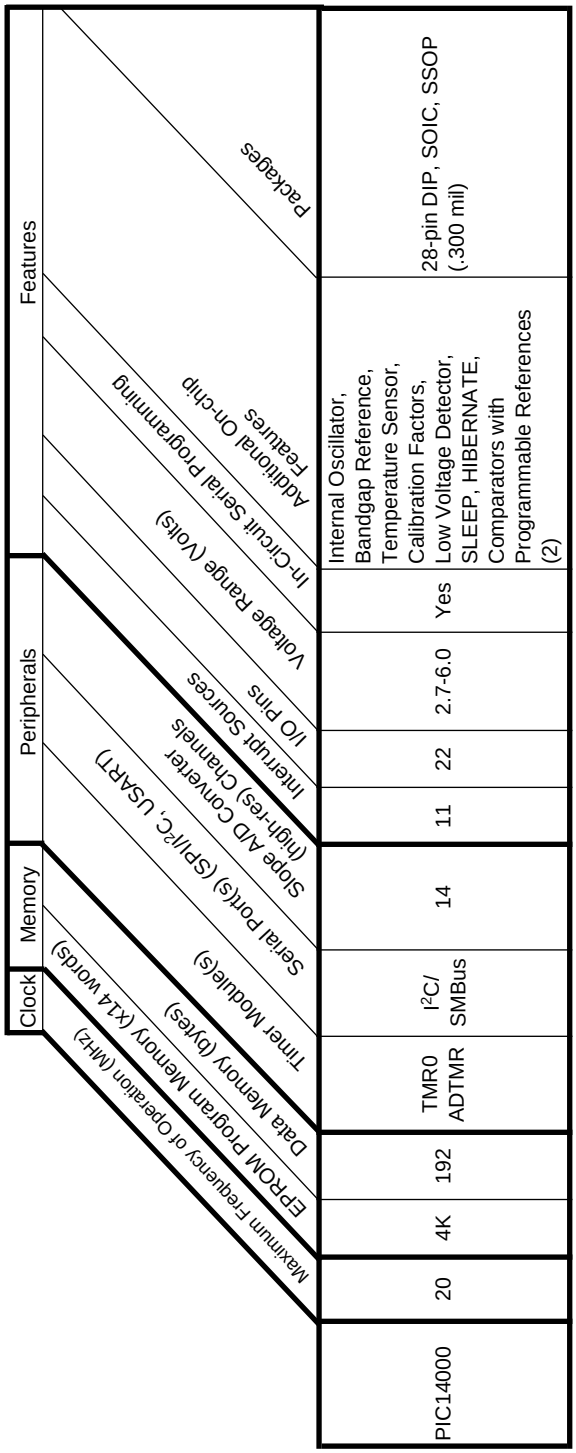
NOTES:

APPENDIX E: PIC16/17 MICROCONTROLLERS

E.1 PIC14000 Devices



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Device: **PIC16C64X & PIC16C66X** Literature Number: **DS30559A**

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2. How does this document meet your hardware and software development needs?

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4. What additions to the data sheet do you think would enhance the structure and subject?

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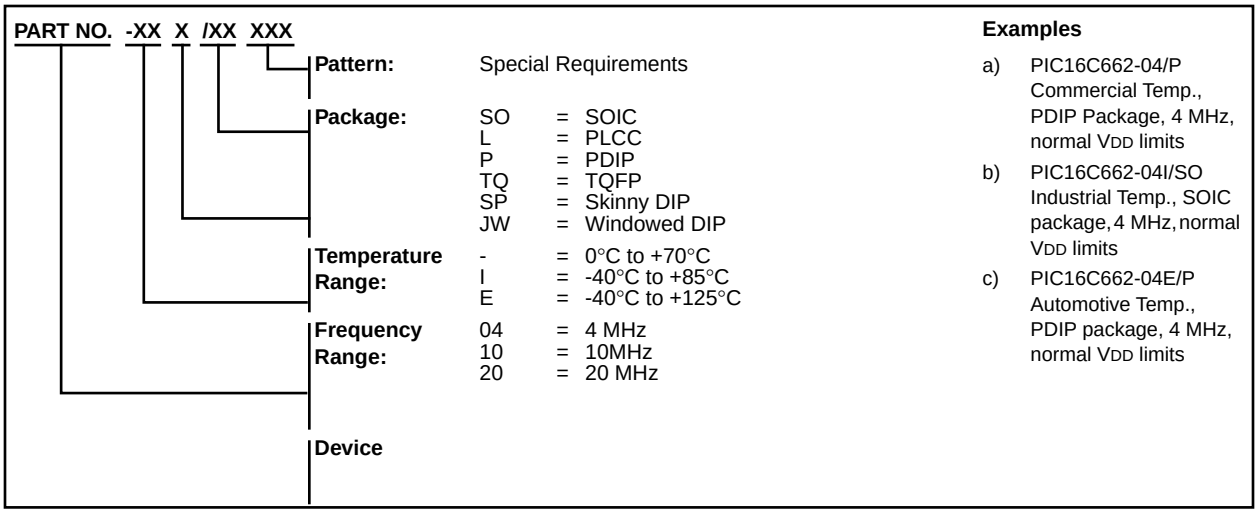
6. Is there any incorrect or misleading information (what and where)?

7. How would you improve this document?

8. How would you improve our software, systems, and silicon products?

NOTES:

PIC16C64X & PIC16C66X PRODUCT IDENTIFICATION SYSTEM



Please contact your local sales office for exact ordering procedures.

JW devices are UV erasable and can be programmed to any device configuration. JW devices meet the electrical requirements of each oscillator type (including LC devices).

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